

L Number	Hits	Search Text	DB	Time stamp
1	272	((encapsul\$3 or epoxy) near cur\$3) and (cur\$3 with (microwave or frequency or mhz or hz or megahertz))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/11 05:47
2	86	((((encapsul\$3 or epoxy) near cur\$3) and (cur\$3 with (microwave or frequency or mhz or hz or megahertz))) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/11 05:48
3	73	((((encapsul\$3 or epoxy) near cur\$3) and (cur\$3 with (microwave or frequency or mhz or hz or megahertz))) and (chip or die)) and (@ad<19991230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/11 05:49

## (g) Epoxy Cure

The curing radiation is suitably UV radiation having wavelengths of between 250 and 800 nm, preferably between 250 and 450 nm. However, electron beam radiation, microwave and heat radiation may also be employed as curing radiation although these are less preferred.

## Microwave Cure

2/90, 96

260/39.5

117/62

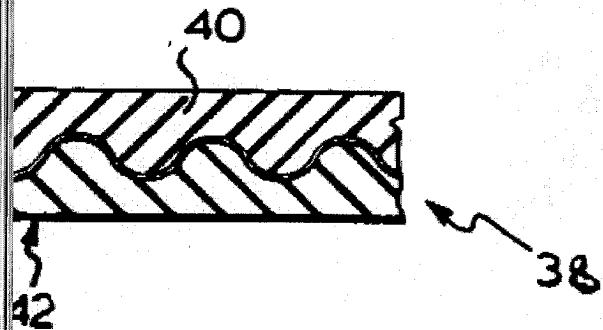
260/17

260/873

428/345

in the presence of oxygen, the composition is solvent free and cures to a mass resistant to water; surfaces of the adhesive exposed to oxygen remain tacky and uncured; the adhesive is especially useful in window structures in which adhesion of the tacky surface excludes the cure-inhibiting oxygen and the tacky surface can be cured by UV radiation passing through the window glass.

4 Claims, 4 Drawing Sheets



In the apparatus 70 of the present

